

A DEVICE AND METHOD FOR PROVIDING ACCESS TO A SIGNAL OF A  
FLIP CHIP SEMICONDUCTOR DIE

ABSTRACT OF THE DISCLOSURE

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A device and method for providing access to a signal of a flip chip semiconductor die. A hole is bored into a semiconductor die to a test probe point. The hole is backfilled with a conductive material, electrically coupling the test probe point to a signal redistribution layer. A conductive bump of the signal 10 redistribution layer is electrically coupled to a conductive contact of a package substrate. An external access point of the package substrate is electrically coupled to the conductive contact, such that signals of the flip chip semiconductor die are accessible for measurement at the external access point.